Parameter	Symbol	Rating	Unit
Drain Source Voltage	V_{DSS}	500	V

/ Electrical Characteristics(Ta=25)

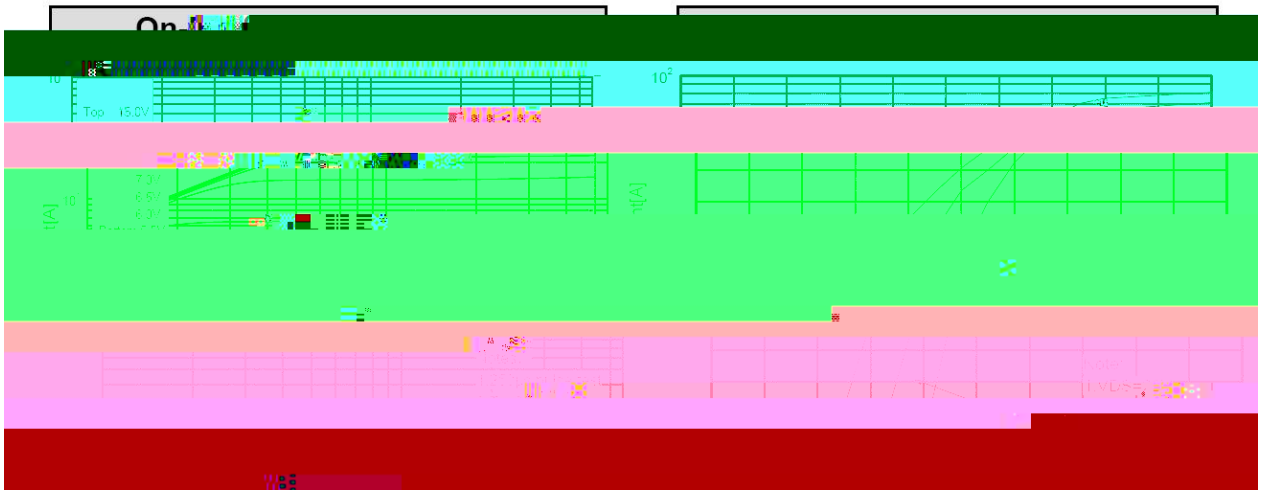
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	500			V
Drain-Source Leakage Current	I_{DSS}	V_{DS}=500V V_{GS}=0V			1	μA
Gate- Source Leakage Current Forward	I_{GSSF}	V_{DS}=0V V_{GS}=+30V			+100	nA
Gate-Source Leakage Current Reverse	I_{GSSR}	V_{DS}=0V V_{GS}=-30V			-100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}= V_{GS} I_D=250μA	3.0		5.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS} =10V I_D=13A		0.17	0.2	Ω
Input Capacitance	C_{iss}	V_{DS}=25V V_{GS} =0V, f=1.0MHZ		3360		pF
Output Capacitance	C_{oss}			280		
Reverse Transfer Capacitance	C_{rss}			35		
Total Gate Charge		V_{GS}=10V V_{DS}=400V I_D=26A (Note 1, 2)		81	120	nC
Gate to Source Charge				23		
Gate to Drain Charge				35		
	$t_{D(ON)}$	V_{DD}=250V I_D=26A R_G=25Ω (Note 1, 2)		80	170	ns
Rise Time	t_R			2500	500	
Turn-OFF Delay Time	$t_{D(OFF)}$			200	400	
Fall-Time	t_F			155	320	
Maximum Body-Diode Continuous Current	I_S				26	A
Maximum Body-Diode Pulsed Current	I_{SM}				104	A
Drain-Source Diode Forward Voltage	V_{SD}	I_S=26A V_{GS}=0V			1.4	V
Body Diode Reverse Recovery Time	T_{rr}	I_S=26A V_{GS}=0V dIF/dt=100A/μs (Note 1)		530		ns
Body Diode Reverse Recovery Charge	Q_{RR}			8.2		μC

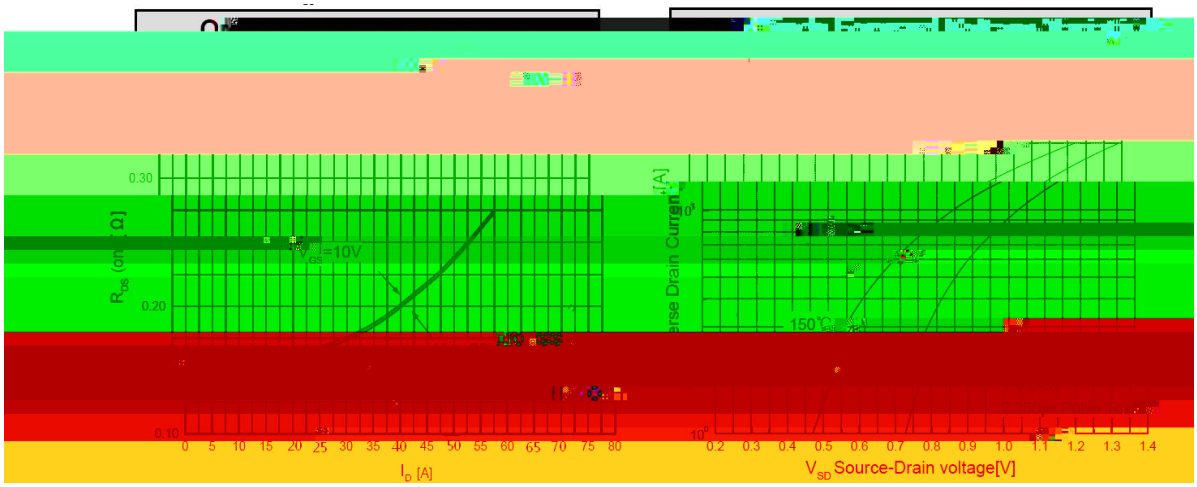
1. ≤300μs ≤2%
2.

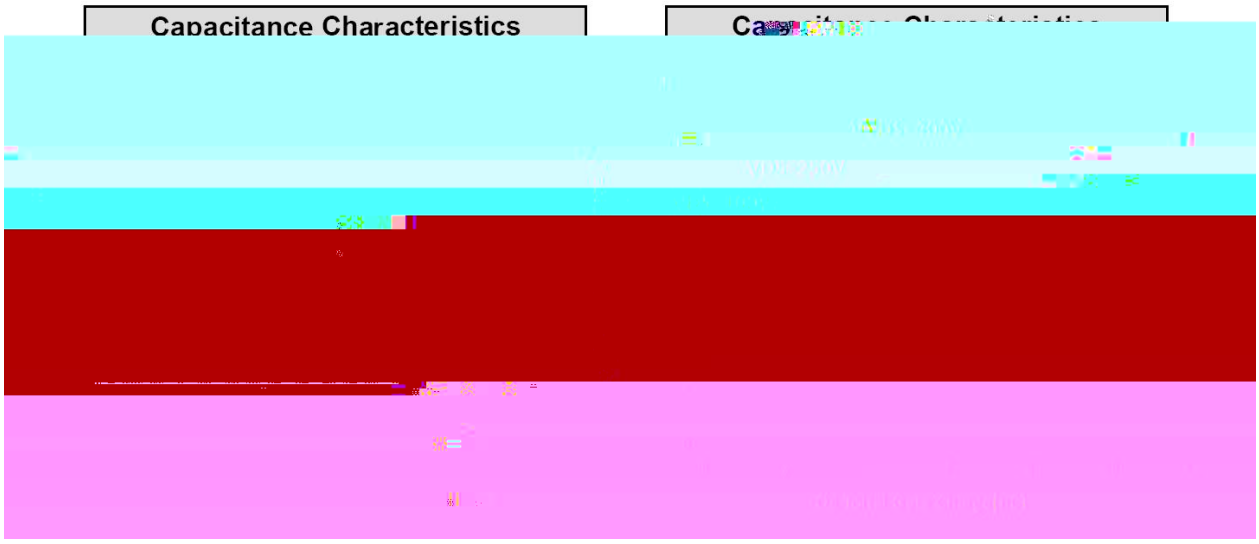
ote:

1. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%.
2. Essentially independent of operating temperature.

/ Electrical Characteristic Curve

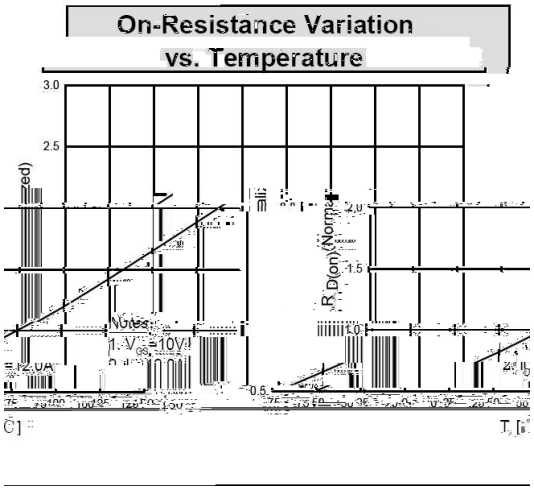


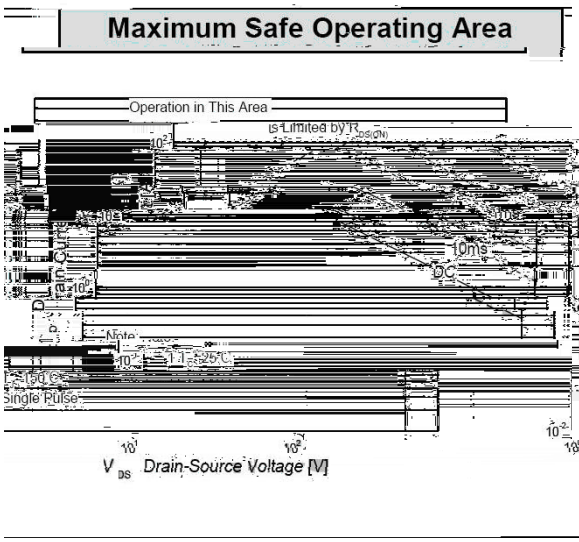


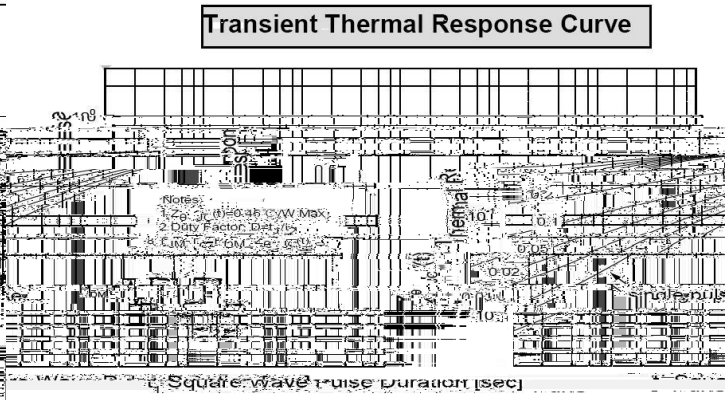


/ Electrical Characteristics(Ta=25)

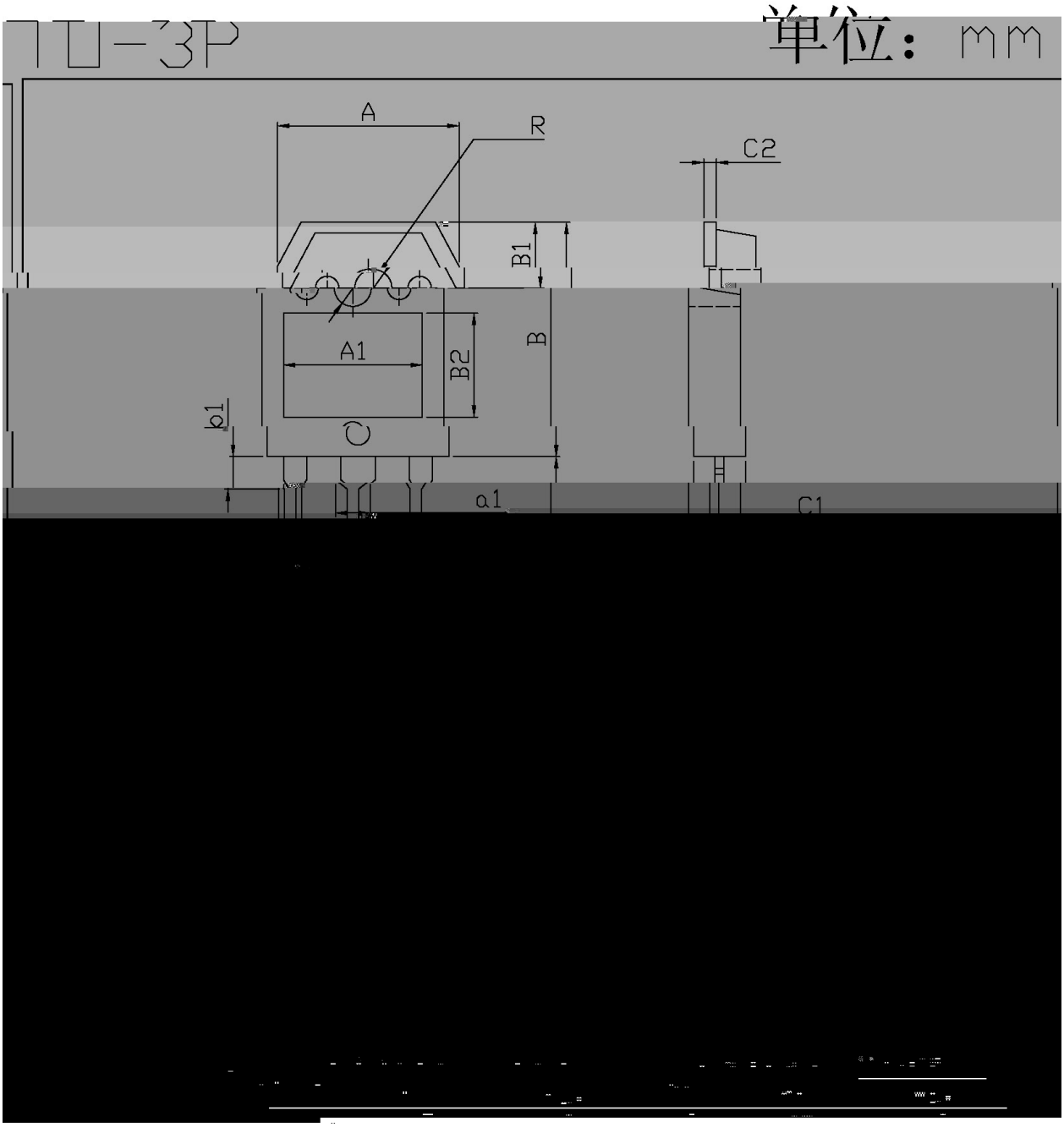




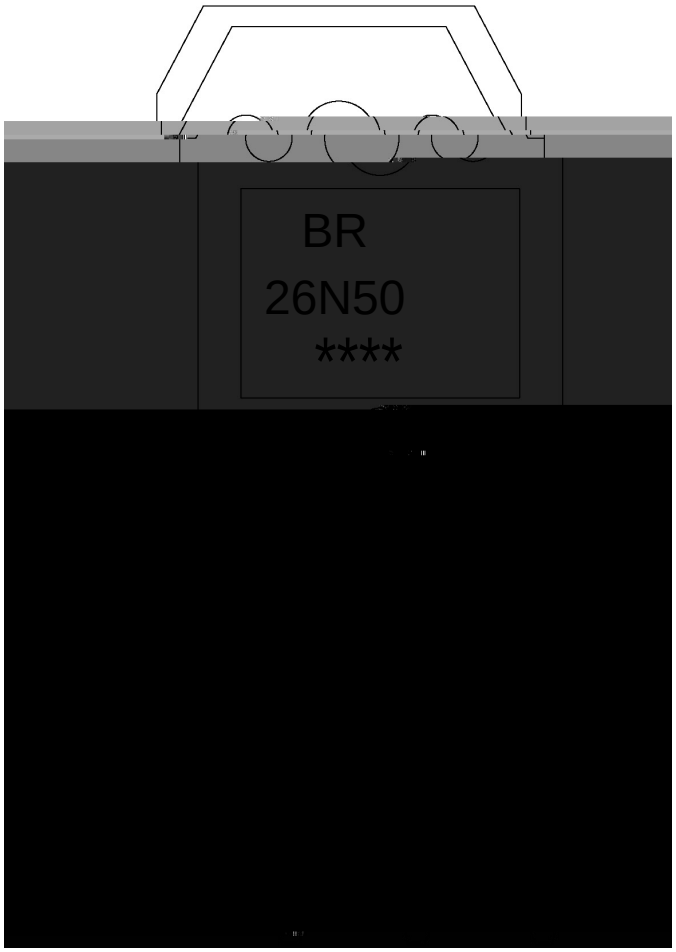




/ Package Dimensions



/ Marking Instructions



BR:

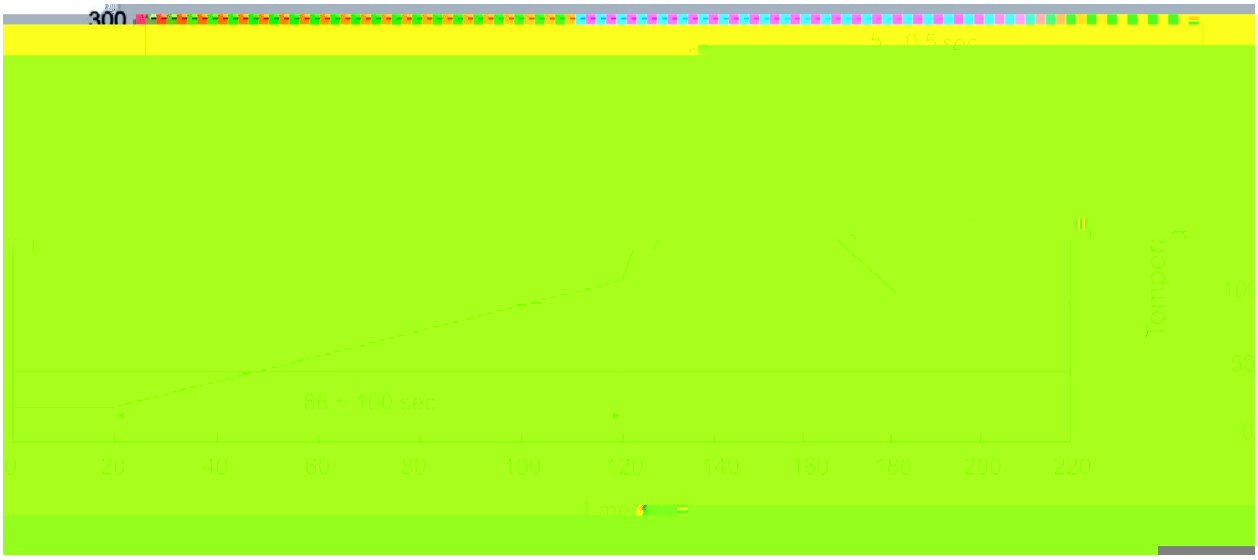
26N50

****

Note:

BR:	Company Code.
26N50:	Product Type.
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



					Note:
1		25	150	60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2		255±5		5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3			2 10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp:270±5	Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type 封装形式	Units 已装数量					Dimension 已装尺寸 (unit: mm^3)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱